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Standard for Extensions to Standard Test Interface Language (STIL) for Semiconductor Design Environments

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STANDARD FOR EXTENSIONS TO STANDARD TEST INTERFACE LANGUAGE (STIL) FOR SEMICONDUCTOR DESIGN ENVIRONMENTS

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IEEE Std	FDIS	Report on voting
1450.1(2005)	93/248/FDIS	93/259/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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IEEE Standard for Extensions to Standard Test Interface Language (STIL) (IEEE Std 1450™-1999) for Semiconductor Design Environments

Sponsor

Test Technology Standards Committee
of the
IEEE Computer Society

Approved 9 June 2005

IEEE-SA Standards Board

Abstract: Standard Test Interface Language (STIL) provides an interface between digital test generation tools and test equipment. Extensions to the test interface language (contained in this standard) are defined that (1) facilitate the use of the language in the design environment and (2) facilitate the use of the language for large designs encompassing subdesigns with reusable patterns.
Keywords: advanced scan architecture, core, environment, fail feedback, lockstep, parallel patterns, parameterized data, pattern tiling, pragma, signal variable, system on chip (SoC), test protocol

IEEE Introduction

The Standard Test Interface Language (STIL) was initially developed by an ad hoc consortium of automatic test equipment vendors (ATE), electronic design automation vendors (EDA), and integrated circuit (IC) manufacturers to address the lack of a common solution for transferring digital test data from the generation environment to the test equipment.

The scope of the initial STIL standard was limited to satisfy the basic needs of pattern definition. Additional capabilities are developed as separate projects resulting in separate (dot) extensions to the initial STIL standard. The scope of this extension is defined in 1.1 and is primarily to address design needs.

Whereas the initial STIL standard was developed by reviewing many languages already in existence in the industry, this standard has been developed by inventing new capabilities in support of new device designs. The new language constructs have been added such that they do not alter in any way the initial definition of STIL, yet are syntactically compatible with the initial STIL language.

Much of the work to develop and validate these extensions has been done by prototyping on the part of the contributing companies.

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STANDARD FOR EXTENSIONS TO STANDARD TEST INTERFACE LANGUAGE (STIL) (IEEE Std 1450™-1999) FOR SEMICONDUCTOR DESIGN ENVIRONMENTS

1. Overview

STIL is an evolving standard being developed in support of various needs for interfacing between test generation tools and test equipment. IEEE Std 1450-1999 (STIL.0) [B3][1] forms the basis for this evolution. New "dot" standards (like this one) are being developed to address specific needs beyond STIL.0.

This (STIL.1) standard addresses design-related aspects of digital test data. This standard can also be viewed as the addition of advanced features to the STIL.0 baseline to allow for the usage of STIL in more complex applications, while leaving the basic standard unchanged as a vehicle for transmitting basic test data. The following is a brief overview of the new features in STIL.1 to support advanced applications such as (1) embedded cores,[2] (2) families of test patterns, (3) mapping to automated test equipment (ATE) systems,[3] (4) mapping to simulation, and (5) devices with advanced design for test (DFT). Please see Annex O for a list of specific statements for each of these features.

Environment mapping: Data for a device exist in many forms and in many other software environments. Examples include (1) simulation environment, (2) static analysis environment, (3) specific ATE system environment. The STIL Environment block is a new mechanism to relate STIL data to these other environments. No assumptions, expectations, or limitations are imposed on the other environments. It is just a way of relating one to the other.

Parameterized data: Much of STIL data are declarative in nature (i.e., it defines various static attributes of a device or pattern set). The addition of constant declarations, IntegerConstant and WFCConstant, allows a data set to be created that applies to a family of devices.

Complex test protocol definition: Test protocol definitions are usually contained in STIL procedures or MacroDefs and are used to specify the application of a series of data values to a device. STIL.0 supports scan chain data passing and simple WaveformCharacter (WFC) data passing via the # and % characters. STIL.1 enhances this capability by allowing the use of data substitution from SignalVariables and integer-

[1]The numbers in brackets correspond to those of the bibliography in Annex P.

[2]This standard contains syntax in support of embedded cores. See IEEE Std 1450.6™-2005 (Core Test Language) [B5] for the complete specification.

[3]This standard contains syntax in support of ATE systems. See IEEE P1450.3™ (Test Resource Constraints) [B4] for the complete specification.

Complex test protocol definition: Test protocol definitions are usually contained in STIL procedures or MacroDefs and are used to specify the application of a series of data values to a device. STIL.0 supports scan chain data passing and simple WaveformCharacter (WFC) data passing via the # and % characters. STIL.1 enhances this capability by allowing the use of data substitution from SignalVariables and integer-expressions. STIL.1 also enhances the functionality of Loops and Vectors and adds If/While decisions on pattern statements. These capabilities are needed for BIST, embedded cores, and various test access mechanisms.

Advanced scan architecture: Advanced DFT techniques require additional capabilities beyond what is defined in STIL.0, which includes multistate scan cells, reconfigurable scan-chains, and scan-chain indexing.

Run-time pattern decisions: The If, Else, While, and LoopData are new STIL.1 constructs that have been added for specification of pattern activity. These statements are needed in the specification of patterns to be run in the simulation environment. Although there is no standardization among ATE systems on run-time instructions for pattern execution, it is anticipated that restricted versions of these statements will be incorporated into ATE test patterns.

Pattern burst options: New variations on the PatternBurst have been added to allow for patterns running in parallel, patterns running in LockStep, and patterns that can be reordered. For parallel pattern execution, the specification for how the patterns fit together can be specified with the Fixed and Extend statements.

Enhanced user extensibility: The UserKeyword extensibility defined in STIL.0 has been extended to allow keywords to be defined on a per-block-type basis.

Signal relationships: Additional syntax is provided to allow the specification of relationships between signals. This process is preformed via \m to map WFCs to another WFC, \j to join WFCs, Extend to define behavior of signals beyond the bounds of a given pattern, and Fixed to restrict any further changes to signals within a pattern.

Fail feedback: Three new features are added to facilitate the processing of failure data from an ATE system back to design tools. The first is the X or cross-reference statement that allows the specification of where in a pattern/vector sequence a failure occurs. The second is the FailFeedback block for reporting fails. The third is the S/s timing event that allows for the specification of a data capture protocol for the purpose of capturing bulk fail data for processing.

1.1 Scope

Structures are defined in STIL to support usage as semiconductor simulation stimulus, including (1) mapping signal names to equivalent design references, (2) interface between scan and built-in self test (BIST) and the logic simulation, (3) data types to represent unresolved states in a pattern, (4) parallel or asynchronous pattern execution on different design blocks, and (5) expression-based conditional execution of pattern constructs.

Structures are defined in STIL to support the definition of test patterns for sub-blocks of a design[4] (i.e., embedded cores) such that these tests can be incorporated into a complete higher level device test.

Structures are defined in STIL to relate fail information from device testing environments back to original stimulus and design data elements.

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[4]Syntax in this document that is used in the definition of patterns for sub-blocks is summarized in Annex O.